

I. AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A method for processing a semiconductor industry sale pricing decision comprising:

building a case document based on customer information and account sales information, wherein the customer information includes information about a level of technology required to produce a semiconductor product for a customer;

providing the case document to a case analyzer;

providing internal information to the case analyzer, wherein the internal information includes information about a level of utilization of manufacturing equipment that would be used to produce the semiconductor product; and

generating a case summary document by the case analyzer, wherein the generating includes calculating a price based in part on the level of utilization of manufacturing equipment and the level of technological complexity;

wherein the case summary document includes a pricing option associated with a product or service that is to be provided for the customer.

2. (Original) The method of claim 1 further comprising:
making a pricing decision using the case summary document.

3. (Original) The method of claim 2 further comprising:
adjusting a database based on the pricing decision.

4. (Original) The method of claim 2 further comprising:
adjusting a product price within a range based on the pricing decision.

5. (Original) The method of claim 2 wherein the pricing decision is provided to the customer and the account sales.

6. (Original) The method of claim 1 wherein the customer information includes a quantity of a product that is needed and a date when the product is needed.

7. (Original) The method of claim 1 wherein the account sales information includes a history of price quotes offered to the customer.

8. (Original) The method of claim 1 further comprising:
reviewing the case document before providing it to the case analyzer to make a decision whether to provide the case document to the case analyzer.

9. (Original) The method of claim 8 wherein the decision is made to provide the case document to the case analyzer whereby regional information is added to the case document before the case document is provided to the case analyzer.

10. (Original) The method of claim 9 wherein the regional information includes data on the financial impact of the pricing decision.

11. (Original) The method of claim 8 wherein the decision is made not to provide the case document to the case analyzer and that decision is provided to the customer and the account sales.

12. (Original) The method of claim 1 wherein the internal information provided to the case analyzer includes market data.

13. (Previously Presented) A method for processing a semiconductor industry pricing decision comprising:

receiving customer order information;

providing account sales information that is specific to the customer order information;

building a case document based on the customer order information and the account sales information;

providing the case document to a case analyzer program;

providing internal information to the case analyzer program; and
generating a case summary document by the case analyzer program, wherein the
generating includes calculating a price based in part on a level of utilization of manufacturing
equipment and a level of technological complexity;
wherein the case summary document includes a pricing option associated with a product
or service that is to be provided for the customer.

14. (Original) The method of claim 13 further comprising:
making a pricing decision using the case summary document.

15. (Original) The method of claim 14 further comprising:
adjusting a database based on the pricing decision.

16. (Original) The method of claim 14 further comprising:
adjusting a product price within a range based on the pricing decision.

17. (Original) The method of claim 14 wherein the pricing decision is provided to the
customer and the account sales.

18. (Original) The method of claim 13 wherein the customer order information
includes a quantity of a product that is needed and a date when the product is needed.

19. (Original) The method of claim 13 wherein the account sales information
includes a history of price quotes offered to the customer.

20. (Original) The method of claim 13 further comprising:
reviewing the case document before providing it to the case analyzer program to make a
decision whether to provide the case document to the case analyzer program.

21. (Original) The method of claim 20 wherein the decision is made to provide the case document to the case analyzer program whereby regional information is added to the case document before the case document is provided to the case analyzer.

22. (Original) The method of claim 21 wherein the regional information includes data on the financial impact of the pricing decision.

23. (Original) The method of claim 20 wherein the decision is made to not provide the case document to the case analyzer program and that decision is provided to the customer and the account sales.

24. (Original) The method of claim 13 wherein the internal information provided to the case analyzer program includes market data.

25-45. (Cancelled)

46. (Currently amended) The method of claim 1 wherein the semiconductor industry sale pricing decision is a decision on whether to accept a proposed price to be charged to the customer for producing a requested quantity of the semiconductor product, wherein producing the semiconductor product requires a number of mask layers, and wherein the ~~level of technological complexity is related to~~ calculating is based in further part on the number of mask layers.

47. (Currently amended) The method of claim 1 wherein the case summary further includes information regarding how the semiconductor industry sale pricing decision ~~may affect~~ affects the level of utilization of manufacturing equipment.

48. (Currently amended) The method of claim 1 wherein the semiconductor industry sale pricing decision relates to a price ~~to be charged to the customer~~ for producing a quantity of semiconductor wafers, each semiconductor wafer having a number of semiconductor dies,

wherein the price calculated in the generating step is a die price that is derived at least in part from an estimated yield of saleable semiconductor dies from a semiconductor wafer.

49. (Previously Presented) The method of claim 1 wherein the price calculated in the generating step is a wafer price that is a multiple of a wafer production cost, wherein the multiple is chosen based on the level of technological complexity.

50. (Previously Presented) The method of claim 1 wherein the case summary document further includes a comparison to at least one other customer using similar technology.

51. (Previously Presented) The method of claim 1 wherein the case summary document further includes a comparison to at least one other customer in a different geographic sales region.

52. (Previously Presented) The method of claim 5 further comprising:
providing the customer and the account sales with a reason for the pricing decision.